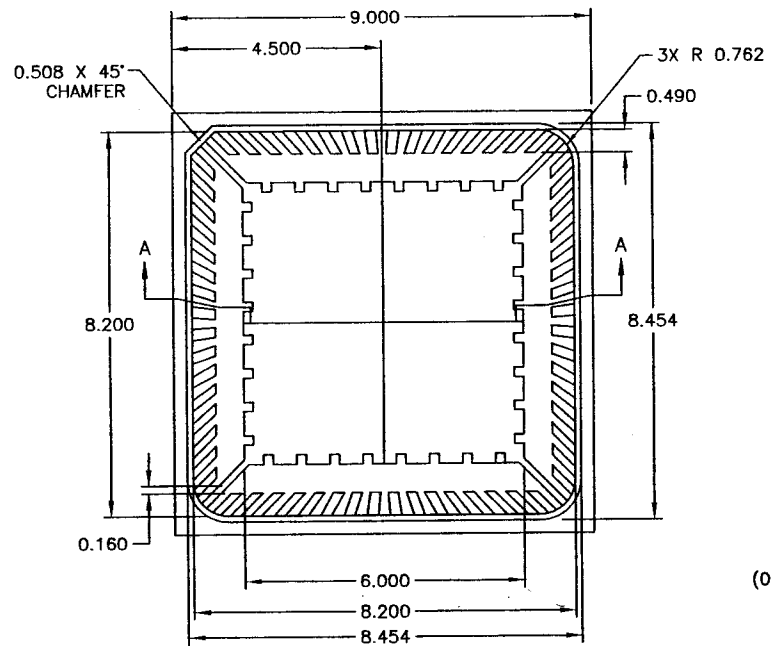
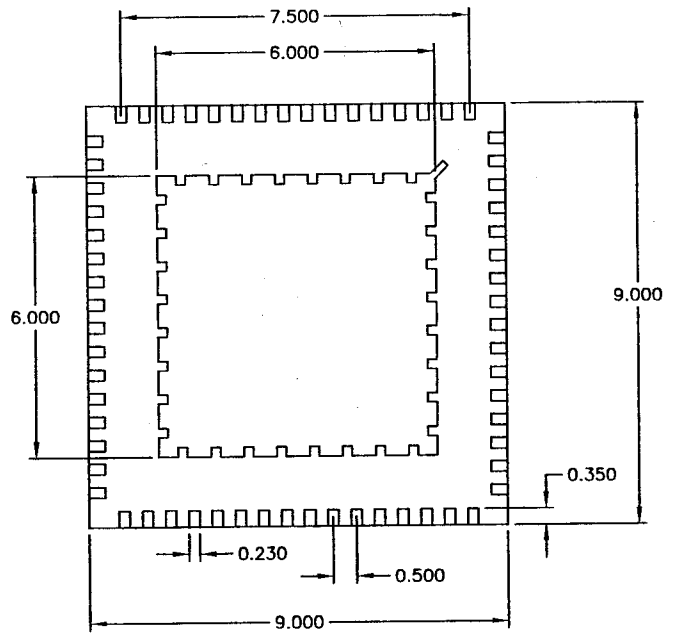
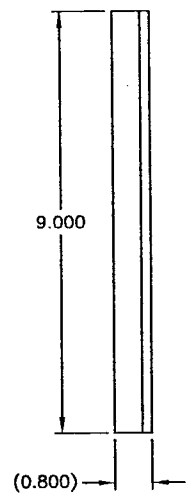


# SSM P/N QFN06401

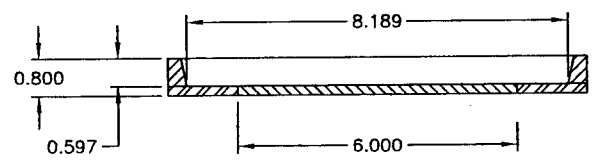
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
		PRODUCTION RELEASE	



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
  2. LEAD FINISH: FULL GOLD PLATE.
  3. LEAD FRAME: COPPER, 194 FH.
  4. LEAD FINISH: FULL GOLD PLATE.
  5. FRAME THICKNESS: 0.2030 ± 0.0076
  6. DIE PAD: 6.000 X 6.000
  7. JEDEC OUTLINE: MO-220.

 THIRD ANGLE PROJECTION	DRAWN BY	DATE
	APP BY	DATE
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XX ± 0.15 X.XXXX ± --- X.XXX ± 0.100 ANGLES: ± 1°		
DO NOT SCALE DRAWING		

64 Lead 9mm x 9mm  
**QFN9X9-064 REV 1**

